

(c) Amendments to the Claims

Please cancel claims 2-5 without prejudice or disclaimer of subject matter.

Kindly amend claim 1 as follows. A detailed listing of the claims that are or were in the application is provided.

1. (Currently Amended) A method for modifying a surface of a substrate to be processed, by utilizing microwave surface-wave plasma, said method comprising the steps of:
 - maintaining the substrate at a temperature ~~of the substrate to a~~ ~~temperature~~ which substantially prevents a material injected by a plasma process into the substrate from diffusing in the substrate, and provides an anneal effect;
 - introducing process gas including the material into a plasma process chamber;
 - generating plasma in the plasma process chamber; and
 - changing at least once an electron temperature of the plasma,

wherein said changing step changes a distance between a generation part for generating the plasma and a stage for mounting the substrate to be processed.